

## NTB13N10G-VB Datasheet N-Channel 100-V (D-S) MOSFET

PRODUCT SUMMARY				
V <sub>(BR)DSS</sub> (V)	R <sub>DS(on)</sub> (Ω)	I <sub>D</sub> (A)		
100	0.100 at V <sub>GS</sub> = 10 V	20		

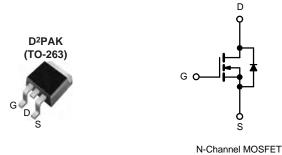
#### **FEATURES**

- Trench Power MOSFET
- 175 °C Junction Temperature
- Low Thermal Resistance Package
- 100 % R<sub>g</sub> Tested

#### **APPLICATIONS**

• Isolated DC/DC Converters





<b>ABSOLUTE MAXIMUM RATINGS</b>	T <sub>C</sub> = 25 °C, unless oth	erwise noted			
Parameter		Symbol	Limit	Unit	
Drain-Source Voltage		V <sub>DS</sub>	100	V	
Gate-Source Voltage		V <sub>GS</sub>	± 20	- V	
Continuous Drain Current ( $T_1 = 175 ^{\circ}C$ )	T <sub>C</sub> = 25 °C	L.	20		
Continuous Drain Current $(1_J = 175^{\circ}C)$	T <sub>C</sub> = 125 °C		16	A	
Pulsed Drain Current		I <sub>DM</sub>	70		
Avalanche Current	L = 0.1 mH	I <sub>AS</sub>	20		
Single Pulse Avalanche Energy <sup>b</sup>	L = 0.1 min	E <sub>AS</sub>	200	mJ	
Mariana Diasiasiash	T <sub>C</sub> = 25 °C	P	105	14/	
Maximum Power Dissipation <sup>b</sup>	T <sub>A</sub> = 25 °C <sup>d</sup>	– P <sub>D</sub> –	3.75	W	
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stq</sub>	- 55 to 175	°C	

THERMAL RESISTANCE RATINGS					
Parameter		Symbol	Limit	Unit	
Junction-to-Ambient	PCB Mount (TO-263) <sup>d</sup>	R <sub>thJA</sub>	40	°C/W	
Junction-to-Case (Drain)		R <sub>thJC</sub>	0.4	C/VV	

Notes:

a. Package limited.

b. Duty cycle  $\leq$  1 %.

c. See SOA curve for voltage derating.

d. When Mounted on 1" square PCB (FR-4 material).

Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static	-						
Drain-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	$V_{DS} = 0 \text{ V}, I_{D} = 250 \mu\text{A}$	100			V	
Gate-Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_D = 250 \ \mu A$	1		3	V	
Gate-Body Leakage	I <sub>GSS</sub>	$V_{DS} = 0 V, V_{GS} = \pm 20 V$			± 100	nA	
		V <sub>DS</sub> = 100 V, V <sub>GS</sub> = 0 V			1	μA	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	$V_{DS} = 100 \text{ V}, \text{ V}_{GS} = 0 \text{ V}, \text{ T}_{J} = 125 ^{\circ}\text{C}$			50		
		$V_{DS} = 100 \text{ V}, \text{ V}_{GS} = 0 \text{ V}, \text{ T}_{J} = 175 ^{\circ}\text{C}$			250		
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} \ge 5 \text{ V}, \text{ V}_{GS} = 10 \text{ V}$	120			А	
		V <sub>GS</sub> = 10 V, I <sub>D</sub> = 20 A		0.100		Ω	
Drain-Source On-State Resistance <sup>a</sup>	r <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 20 A, T <sub>J</sub> = 125 °C		0.110			
		V <sub>GS</sub> = 10 V, I <sub>D</sub> = 20 A, T <sub>J</sub> = 175 °C		0.120			
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = 15 V, I <sub>D</sub> = 20 A	25			S	
Dynamic <sup>b</sup>							
Input Capacitance	C <sub>iss</sub>	V <sub>GS</sub> = 0 V, V <sub>DS</sub> = 25 V, f = 1 MHz		950		pF	
Output Capacitance	C <sub>oss</sub>			280			
Reverse Transfer Capacitance	C <sub>rss</sub>			110			
Total Gate Charge <sup>c</sup>	Qg				28	nC	
Gate-Source Charge <sup>c</sup>	Q <sub>gs</sub>	V <sub>DS</sub> = 100 V, V <sub>GS</sub> = 10 V, I <sub>D</sub> = 65 A			4.8		
Gate-Drain Charge <sup>c</sup>	Q <sub>gd</sub>				15		
Gate Resistance	R <sub>g</sub>		0.5	1.7	3.3	Ω	
Turn-On Delay Time <sup>c</sup>	t <sub>d(on)</sub>			8			
Rise Time <sup>c</sup>	t <sub>r</sub>	$\label{eq:VDD} \begin{array}{l} V_{\text{DD}} = 100 \; V,  R_{\text{L}} = 1.5 \; \Omega \\ I_{\text{D}} \cong 65 \; A,  V_{\text{GEN}} = 10 \; V,  R_{\text{g}} = 2.5 \; \Omega \end{array}$		120		ns	
Turn-Off Delay Time <sup>c</sup>	t <sub>d(off)</sub>			25			
Fall Time <sup>c</sup>	t <sub>f</sub>			50			
Source-Drain Diode Ratings and Cha	aracteristics 7	r <sub>c</sub> = 25 °C <sup>b</sup>					
Continuous Current	I <sub>S</sub>				65		
Pulsed Current	I <sub>SM</sub>			1	140	A	
Forward Voltage <sup>a</sup>	V <sub>SD</sub>	I <sub>F</sub> = 65 A, V <sub>GS</sub> = 0 V		1.0	1.5	V	
Reverse Recovery Time	t <sub>rr</sub>			130	200	ns	
Peak Reverse Recovery Current	I <sub>RM(REC)</sub>	I <sub>F</sub> = 50 A, di/dt = 100 A/μs		8	12	А	
Reverse Recovery Charge	Q <sub>rr</sub>			0.52	1.2	μC	

Notes:

a. Pulse test; pulse width  $\leq$  300 µs, duty cycle  $\leq$  2 %.

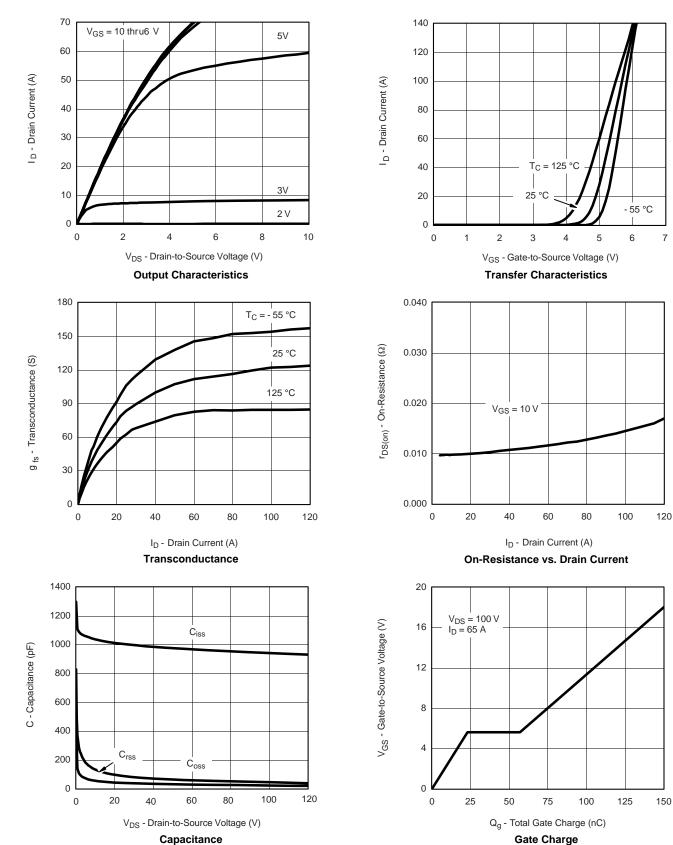
b. Guaranteed by design, not subject to production testing.

c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

Bsemi

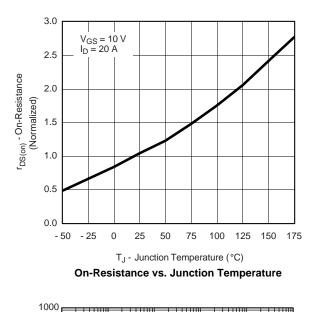


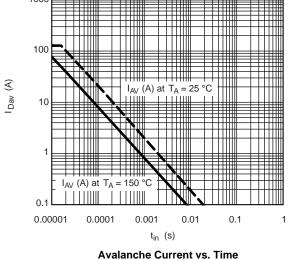


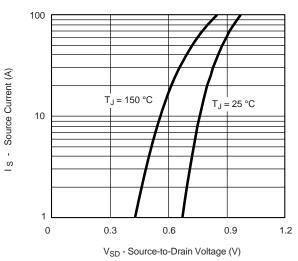
#### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



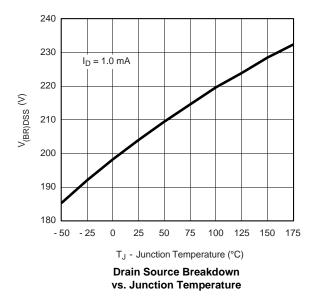
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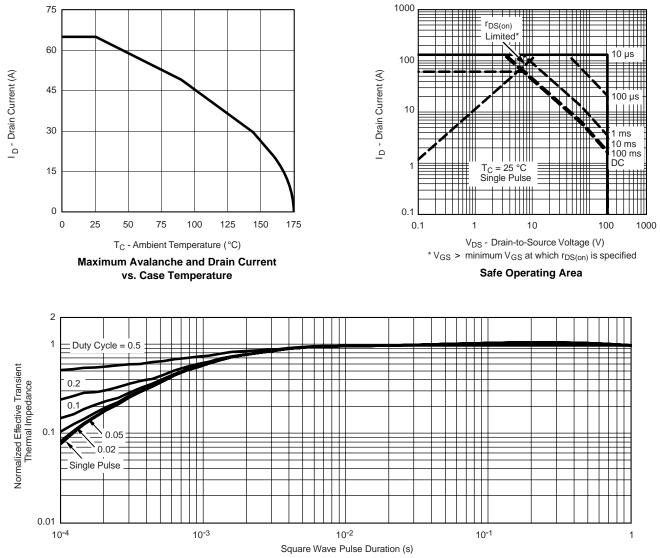
Source-Drain Diode Forward Voltage



## NTB13N10G-VB

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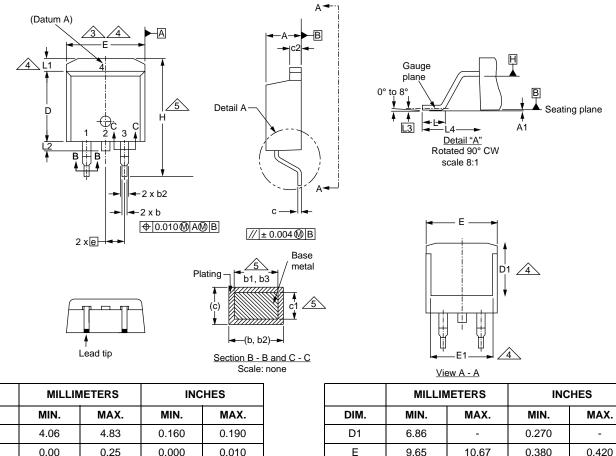
#### THERMAL RATINGS



Normalized Thermal Transient Impedance, Junction-to-Case



#### **TO-263AB (HIGH VOLTAGE)**



E1

е

н

L

L1

L2

L3

L4

6.22

14.61

1.78

-

-

4.78

2.54 BSC

0.25 BSC

\_

15.88

2.79

1.65

1.78

5.28

D	8.38	9.65			
ECN: S-82110-Rev. A, 15-Sep-08 DWG: 5970					

0.51

0.51

1.14

1.14

0.38

0.38

1.14

#### Notes

DIM.

А

A1

b

b1

h2

b3

с

c1

c2

1. Dimensioning and tolerancing per ASME Y14.5M-1994.

0.99

0.89

1.78

1.73

0.74

0.58

1.65

2. Dimensions are shown in millimeters (inches).

4. Thermal PAD contour optional within dimension E, L1, D1 and E1.

0.020

0.020

0.045

0.045

0.015

0.015

0.045

0.330

0.039

0.035

0.070

0.068

0.029

0.023

0.065

0.380

- 5. Dimension b1 and c1 apply to base metal only.
- 6. Datum A and B to be determined at datum plane H.
- 7. Outline conforms to JEDEC outline to TO-263AB.

0.245

0.575

0.070

-

-

0.188

0.100 BSC

0.010 BSC

-

0.625

0.110

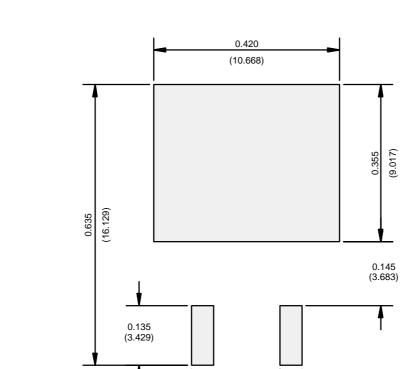
0.066

0.070

0.208

<sup>3.</sup> Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body at datum A.





### **RECOMMENDED MINIMUM PADS FOR D<sup>2</sup>PAK: 3-Lead**

Recommended Minimum Pads Dimensions in Inches/(mm)

0.200

(5.080)

0.050

(1.257)



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